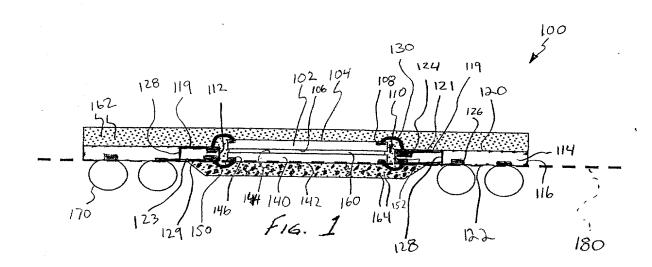
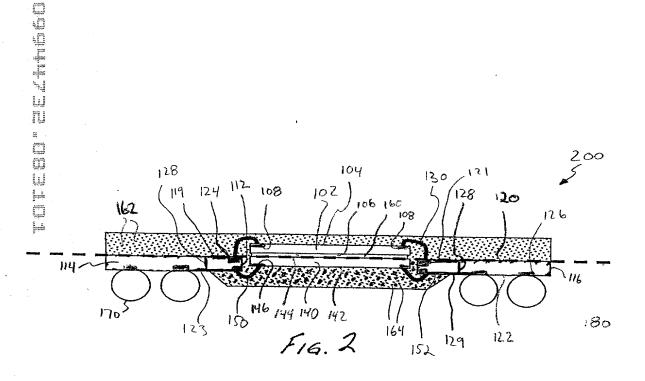
Title: Thin Semiconductor Package Including Stacked Dies

Atty. Docket No.: M-11443 US

Sheet 1 of 6





Title: Thin Semiconductor Package Including Stacked Dies

Atty. Docket No.: M-11443 US

Sheet 2 of 6

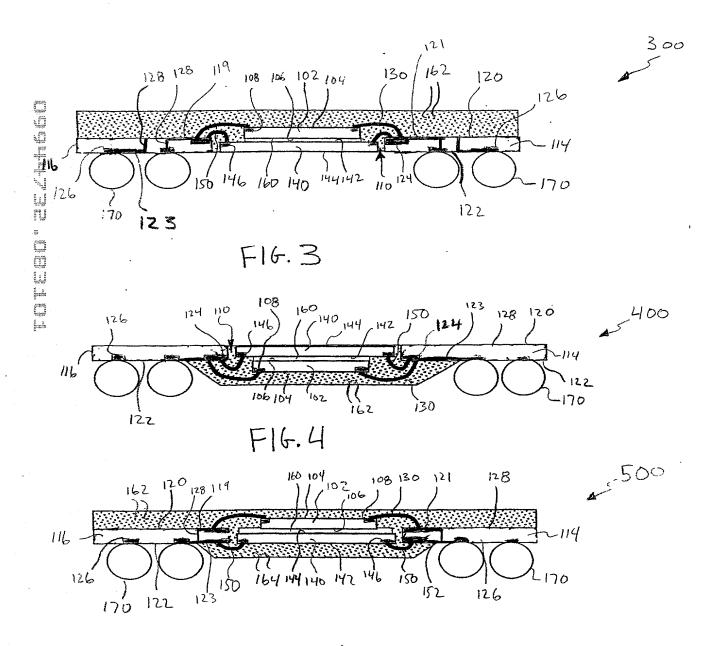
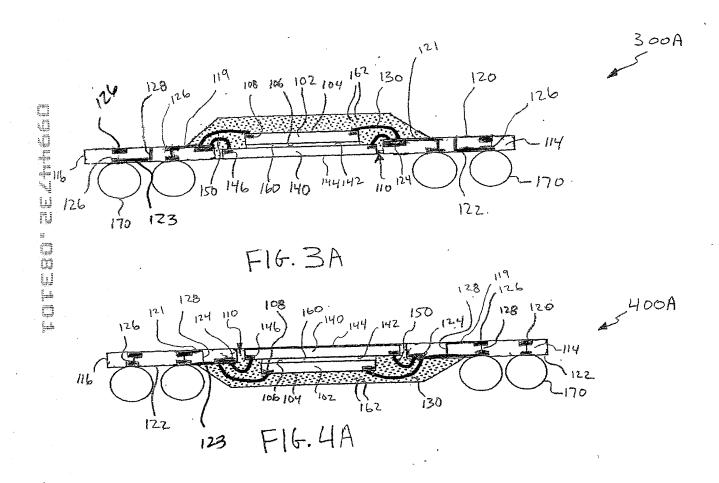


FIG. 5

Title: Thin Semiconductor Package Including Stacked Dies

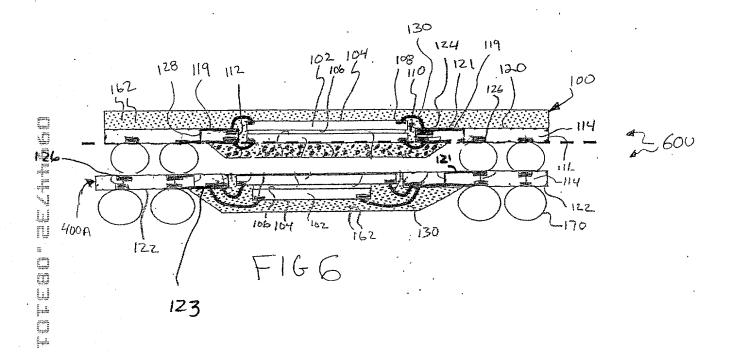
Atty. Docket No.: M-11443 US

Sheet 3 of 6



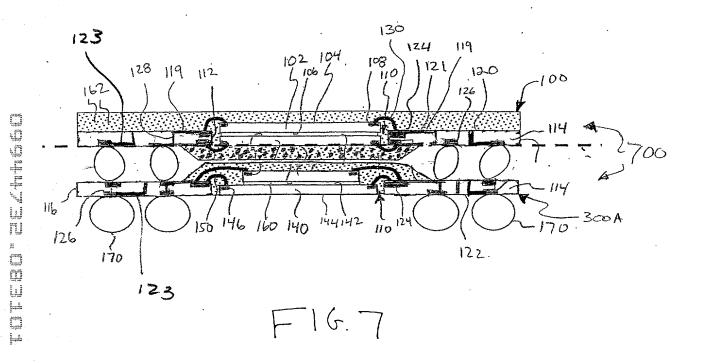
Title: Thin Semiconductor Package Including Stacked Dies

Atty. Docket No.: M-11443 US Sheet 4 of 6



Inventors: Lee John Smith and David Albert Zoba Title: Thin Semiconductor Package Including Stacked Dies

Atty. Docket No.: M-11443 US Sheet 5 of 6



nventors: Lee John Smith and David Albert Zoba Title: Thin Semiconductor Package Including Stacked Dies Atty. Docket No.: M-11443 US

heet 6 of 6

